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PPLICATION NO	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO	CONFIRMATION NO
09 651,790	08 30 2000	Pary Baluswamy	CF 027 PROV.	2095
75	90 11 06 2002			
Samuel E Webb			EXAMINER	
Trask Britt P O Box 2550			PIZARRO CRESPO, MARCOS D	
Salt Lake City,	U1 84110		ART UNIT	PAPER NUMBER
			2814	
			DATE MAILED: 11 06 2002	

Please find below and or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)
Office Action Summary		09/651,790	BALUSWAMY ET AL.
		Examiner	Art Unit
		Marcos D. Pizarro-Crespo	2814
Period fo	- The MAILING DATE of this communication ap r Reply	opears on the cover sheet with the c	orrespondence address
THE N - Exten after S - If the - If NO - Failur - Any re	PRTENED STATUTORY PERIOD FOR REPIDATION OF THIS COMMUNICATION.  Sions of time may be available under the provisions of 37 CFR 1.  Sions of time may be available under the provisions of 37 CFR 1.  Sions of time may be available under the provisions of 37 CFR 1.  Sions of time may be available under the provisions of 37 CFR 1.  Sions of time may be available under the provisions of 37 CFR 1.  Sions of time may be available under the maximum statutory period for reply within the set or extended period for reply will, by statution ply received by the Office later than three months after the mailing patent term adjustment. See 37 CFR 1.704(b).		nely filed s will be considered timely, the mailing date of this communication. D (35 U.S.C. § 133).
1) 🗔	Responsive to communication(s) filed on $\underline{26}$	August 2002 .	
2a)□	This action is <b>FINAL</b> . 2b)⊠ T	his action is non-final.	
3)□ Dispositio	Since this application is in condition for allow closed in accordance with the practice under on of Claims		
4)	Claim(s) <u>1-21</u> is/are pending in the applicatio	n.	
4	a) Of the above claim(s) <u>1-15</u> is/are withdraw	n from consideration.	
5)	Claim(s) is/are allowed.		
6)[	Claim(s) <u>16-21</u> is/are rejected.		
7) 🗌	Claim(s) is/are objected to.		
8)[]	Claim(s) <u>1-21</u> are subject to restriction and/or	election requirement.	
Application	on Papers		
9)∐ T	he specification is objected to by the Examine	er.	
10)∐ T	he drawing(s) filed on is/are: a)□ acce	•	
	Applicant may not request that any objection to the		
	he proposed drawing correction filed on <u>03 Ja</u>	<u>anuary 2001 and 24 May 2002</u> is: a	a) approved b) disapproved
by the Exan	nner. If approved, corrected drawings are required in re	anly to this Office action	
12)□ T	he oath or declaration is objected to by the Ex		
	nder 35 U.S.C. §§ 119 and 120	Namino,	
_	Acknowledgment is made of a claim for foreig	n priority under 35 H.S.C. & 110/a	\-(d) or (f)
	All b) Some * c) None of:	in priority under 55 5.5.6. § 115(a)	7-(d) or (i).
·	. Certified copies of the priority document	ts have been received	
	C. Certified copies of the priority document		nn No
	Copies of the certified copies of the price application from the International Bu	ority documents have been receive	
	The translation of the foreign language processions.		

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Attorney's Docket Number: 4307 US (99-1193)

Filing Date: 8/20/2000

Claimed Foreign Priority Date: none

Applicant(s): Baluswamy et al.

Examiner: Marcos D. Pizarro-Crespo

### **DETAILED ACTION**

This Office action responds to the amendment (paper no. 17) filed on 8/26/2002.

### Continued Examination Under 37 CFR 1.114

1. A request for a continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after a final rejection. Since this application is eligible for a continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action (paper no. 16) has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 9/18/2002 has been entered.

# Acknowledgment

2. The amendment (paper no. 17) filed on 8/26/2002 in response to the Office action (paper no. 16) mailed on 6/19/2002 has been entered. The present Office action (paper no. 20) is made with all the suggested amendments being fully considered. Accordingly, pending in this Office action are claims 1-21.

The proposed drawing corrections and/or the proposed substitute sneets drawings, filed on 1/3/2001 and on 5/24/2002 have been approved. A proper drawing

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correction or corrected drawings are required in reply to the present Office action to avoid **ABANDONMENT** of the application. The correction to the drawings will not be held in abeyance.

# Claim Rejections - 35 USC § 102

4. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 5. Claims 16-18 are rejected under 35 U.S.C. 102(b) as being anticipated by Deguchi (JP 62-18714).
- 6. Deguchi shows (see, e.g., fig. 1, abstract) all aspects of the instant invention including a method to form an overlay target including a series of raised lines, the method comprising:
  - providing a substrate 10
  - depositing a resist layer 15 over the substrate 10
  - patterning the resist layer **15** to include a resist pattern defining the overlay target including a series of raised lines (see, e.g., fig. 1(a); abstract)
  - etching the substrate **10** to form the overlay target including the resist pattern with the series of raised lines (see, *e.g.*, fig. 1(b))

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- 8. Regarding claim 18, Deguchi deposits the resist layer **15** directly over the semiconductor substrate **10** (see, *e.g.*, fig. 1a).
- 9. Claims 16, 19, and 20, are rejected under 35 U.S.C. 102(b) as being anticipated by Kinoshita (JP 58-90728).
- 10. Kinoshita shows (see, e.g., fig. 3) all aspects of the instant invention including a method to form an overlay target including a series of raised lines, the method comprising:
  - providing a substrate 1
  - depositing a resist layer 26 over the substrate 1
  - patterning the resist layer **26** to include a resist pattern defining the overlay target including a series of raised lines (see, e.g., fig. 3C)
  - retching the substrate 1 to form the overlay target including the resist pattern with the series of raised lines (see, e.g., fig. 3E)
- 11. Regarding claim 19, Kinoshita shows that a material layer **21** may be deposited over the top surface of the semiconductor substrate **1** (see, *e.g.*, fig. 3B).
- 12. Regarding claim 20, Kinoshita shows that the resist layer **26** may be deposited over the material layer **21** and that the step of etching the substrate **1** comprises etching the material layer **21** (see, e.g., figs. 3C-3E).

Claim Rejections - 35 USC § 103

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(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

- 14. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).
- 15. Claim 21 is rejected under 35 U.S.C. 103(a) as being unpatentable over Kinoshita in view of Xu (US 5908319).
- 16. Regarding claim 21, Kinoshita shows most aspects of the instant invention (see paragraph 10-12 above), except for the substrate etching-step comprising wet etching the substrate 1 to form the overlay target. Kinoshita (pp.3/col.1/II.5-12) differently teaches the use of plasma etching.

Xu (col.1/ll.10,11,21,25), on the other hand, teaches that wet etching and plasma etching are known etching techniques that are conventionally used in the fabrication of integrated circuits. In other words, etching is typically performed with either wet etching

of the invention to have a wet-etching step instead of the plasma-etching step in

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Kinoshita's process, as taught by Xu, since etching is typically performed in the semiconductor industry by either plasma-etching or wet-etching.

### Response to Arguments

## 17. The applicants argue:

Deguchi and Kinoshita fail to disclose an overlay target with a series of raised lines as described in the claimed invention. Amended claim 16 recites a method for forming an overlay target including a series of raised lines. The claimed method includes patterning a resist layer to define the overlay target and etching the substrate to form the overlay target including the resist layer with the series of raised lines. Deguchi and Kinoshita fail to use the resist pattern formed in the resist layer to etch that same resist pattern into the substrate. Clearly, Deguchi's resist pattern and the pattern etched into Deguchi's substrate are very different (see, e.g., fig. 1(b)). Likewise, Kinoshita's resist pattern and the pattern etched into Kinoshita's substrate are clearly very different (see, e.g., fig 3E).

The examiner responds:

The feature upon which the applicants rely to support the above argument (*i.e.*, using a resist pattern formed in a resist layer to etch that same resist pattern into a substrate) are not recited in the rejected claim(s). Although the claims are interpreted in light of the specification, limitations from the specification are not read into the claims. See *In re Van Geuns*, 988 F.2d 1181, 26 USPQ2d 1057 (Fed. Cir. 1993).

#### Conclusion

18. Papers related to this application may be submitted directly to Art Unit 2814 by facsimile transmission. Papers should be faxed to Art Unit 2814 via the Art Unit 2814 Fax Center located in Crystal Plaza 4, room 3C23. The faxing of such papers must conform to the notice published in the Official Gazette, 1096 OG 30 (15 November 1989). The Art Unit 2814 Fax Center number is (703) 308-7722 or -7724. The Art Unit

- 19. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Marcos D. Pizarro-Crespo at (703) 308-6558 and between the hours of 9:00 AM to 7:30 PM (Eastern Standard Time) Monday through Thursday or by e-mail via <a href="Marcos.Pizarro@uspto.gov">Marcos.Pizarro@uspto.gov</a>. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy, can be reached on (703) 308-4918.
- 20. Any inquiry of a general nature or relating to the status of this application should be directed to the **Group 2800 Receptionist** at **(703) 308-0956**.
- 21. The following list is the Examiner's field of search for the present Office Action:

Field of Search	Date
U.S. Class / Subclass(es): <b>257</b> /797 <b>438</b> /401, 462, 704, 706, 709-711, 719, 745, 783, 975	10/23/2002
Other Documentation:	
Electronic Database(s): EAST (USPAT, EPO, JPO)	10/23/2002

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Marcos D. Pizarro-Crespo

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